

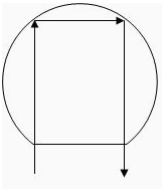
Part Number

Customer

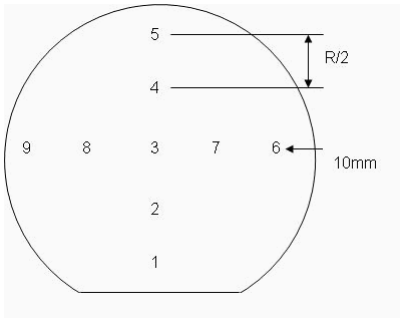
Category	Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm
	2.0	Primary Flat Orientation	<110> +/- 1 degree
	3.0	Primary Flat Length	32.50 +/- 2.50 mm
	4.0	Secondary Flat Orientation	semi std/none
	5.0	Overall Thickness	512.30 +/- 6.00 µm
	6.0	Total Thickness Variation (TTV)	<5.00µm
	7.0	Bow	<60.00µm
	8.0	Warp	<60.00µm
	9.0	Edge Chips	0
	10.0	Edge Exclusion	5mm
HandleSilicon	11.0	Handle Growth Method	FZ
	12.0	Handle Orientation	{111} +/- 1 degree
	13.0	Handle Thickness	482.60 +/- 5.00 µm
	14.0	Handle Doping Type	P
	15.0	Handle Dopant	Boron
	16.0	Handle Resistivity	1000 - 2000 Ohmcm
	17.0	Backside Finish	Lapped and etched with oxide and lasermark
BuriedOxide	18.0	Oxide Type	Thermal
	19.0	Oxide Thickness	22,000.00 +/- 1,000.00 A
	20.0	Oxide formed on	2 um on Handle Wafer and 0.2 um on device
DeviceSilicon	21.0	Device Growth Method	CZ
	22.0	Device Orientation	{111} off 2.5 +/- 0.5 degree
	23.0	Nominal Thickness	27.50 +/- 1.00 µm
	24.0	Distance to device silicon edge from wafer edge	< 2 mm
	25.0	Device Doping Type	P
	26.0	Device Dopant	Boron
	27.0	Device Resistivity	0.004 - 0.006 Ohmcm
	28.0	Buried Layer Implant	none
	29.0	Voids	0
	30.0	Scratches	0
	31.0	Haze	none

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Category	Parameter	Specification	Measurement Method
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Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	

Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.		
	2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.		
	3. 9 point measurement are as shown in the diagram below:		



Additional Information